In the Claims:

- 1-6. (cancelled)
- 7. (original) An integrated circuit structure, comprising:
 - a gate structure formed on a body of semiconductor material;
 - an insulating layer formed opposite said gate structure beneath said semiconductor material;
 - a conducting region within said insulating layer beneath said gate structure, said conducting region having sublithographic width.
- 8. (original) The integrated circuit of Claim 7, wherein said conducting region contacts said semiconductor material.
- 9. (original) The integrated circuit of Claim 7, wherein said conducting region is formed in a trench with sidewalls.
- 10. (original) The integrated circuit of Claim 7, wherein said semiconductor material is silicon.
- 11. (original) The integrated circuit of Claim 7, wherein said conducting region is separated from said semiconductor material by a dielectric material.
- 12-29. (Withdrawn)